

Epiform® FOR ELECTRONIC COMPONENTS – LIQUID RESIN

Electronic Component Epiform® is a resin used for various types of electronic components. Many grades are available, which are suitable for various applications in ceramic capacitors, varistors, thermistors and other small electronic components.

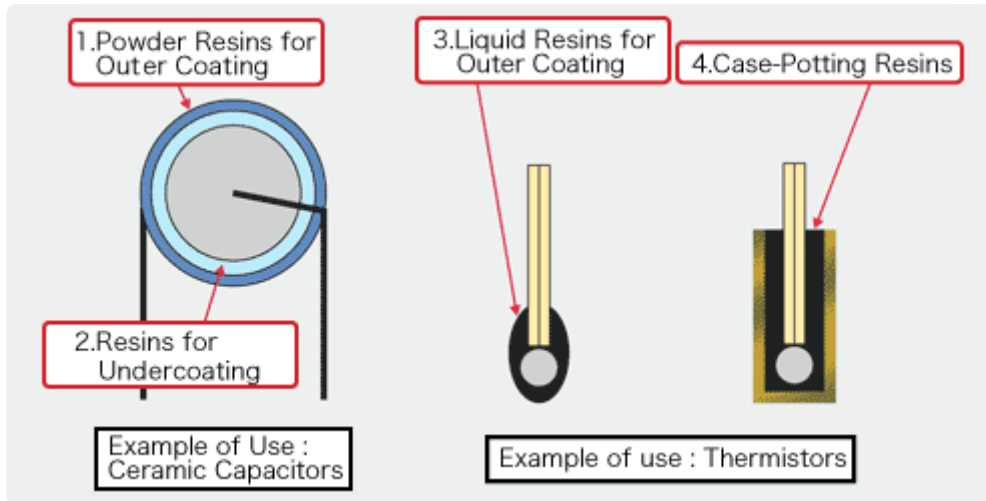
Liquid Resins

Applications	Features	Product Name	Curing Condition (°C/hour)	Mixing Ratio (Weight %)	Pot Life (hour/at 25°C)	Tg Temp (°C)
Undercoating	Moisture Resistance / Fast Cure	E-8501	100/1	One-Part	2months	115
Potting	Low Viscosity / Fast Cure	K-8720	25/24 or 60/1	100/24	0.5	45
	Low Viscosity / Fast Cure	K-8876	100/2	100/38	5	110
	Thermal Conductivity	K-8908	100/5	100/25	16	-16
Outer Coating	Moisture Resistance / Thixotropic property	R-2101 /H-143	100/2	100/20	3	115

All numbers are representative values.

Features

- Liquid Resins for Undercoating.
 - Fast curable/moisture resistance.
 - 1-part resins easy to work with.
- Liquid Resins for Outer Coating.
 - Excellent heat resistance/moisture resistance.
 - High thixotropic properties and stable retention of shape.
- Case-Potting Resins.
 - Low viscosity/fast curable, excellent workability.
 - High thermal conductivity types are also available.



For more information regarding this and other products, please contact us directly.



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